

In the Claims. This Listing of Claims replaces all prior versions and listings of Claims in the application.

1 1. (Original) A method for building a consumable refill, the method
2 comprising the steps of:
3 fabricating a plurality of arrays of consumable parts detachably connected
4 along a first direction;
5 stacking said plurality of said fabricated arrays of parts along a second
6 direction; and
7 providing an adhesive bond between adjacent ones of said stacked
8 plurality of arrays.

1 2. (Original) The method of claim 1 wherein said fabricating step
2 comprises the step of:
3 providing a perforated connection between said consumable parts.

1 3. (Original) The method of claim 1 wherein said step of providing
2 an adhesive bond comprises the step of:
3 adhering adjacent ones of said plurality of arrays using solid rub-on glue.

1 4. (Original) The method of claim 1 further comprising the step of:
2 selecting a strength of said adhesive bond so as to allow separation of an
3 array from an adjacent array only upon experiencing an application of force from
4 an array advancement mechanism.

1 5. (Original) The method of claim 1 further comprising the step of:
2 omitting an attachment to said adhered plurality of arrays of any material
3 requiring removal prior to consumption of said consumable parts in a host device.

1 6. (Original) The method of claim 1 further comprising the step of:
2 destroying the adhesive bond during consumption of the consumable
3 parts.

1 7. (Withdrawn) A staple refill, the refill comprising:
2 a plurality of staple wire layers stacked along a direction normal to a plane
3 of said layers; and
4 an adhesive layer disposed in between each set of adjacent surfaces of
5 said stacked staple wire layers.

1 8. (Withdrawn) The staple refill of claim 7 wherein said adhesive is
2 solid adhesive.

1 9. (Withdrawn) The staple refill of claim 7 wherein said layers are
2 stacked such that all staple wires of said staple wire layers are aligned.

1 10. (Withdrawn) The staple refill of claim 7 wherein said adhesive
2 layers occupy substantially all of a surface area of said each set of adjacent
3 surfaces.

1 11. (Withdrawn) The staple refill of claim 7 wherein said adhesive
2 layers occupy substantially less than all of a surface area of said each set of said
3 adjacent surfaces.

1 12. (Withdrawn) The staple refill of claim 7 wherein said adhesive layer
2 has a bonding force such as to allow separation of a staple wire layer from a
3 remainder of said refill only upon experiencing an application of force from an
4 array advancement mechanism.

1 13. (Withdrawn) A system for fully consuming a staple refill, the system
2 comprising:
3 means for stacking a plurality of staple wire plates; and
4 means for gluing together each set of adjacent staple wire plate surfaces
5 of said stacked plates.

1 14. (Withdrawn) The system of claim 13 further comprising:
2 means for receiving said glued stacked plates into a cartridge;

3 means for separating one of said glued stacked plates from a remainder of
4 said glued stacked plates;
5 means for removing a staple from said separated glued stacked plate; and
6 means for expelling said removed staple and any glue in contact with said
7 removed staple from said cartridge.

1 15. (Withdrawn) The system of claim 13 wherein said means for
2 stacking comprises:
3 means for stacking vertically.

1 16. (Withdrawn) The system of claim 13 wherein said means for
2 stacking comprises:
3 means for stacking said plates such that all staple wires of said stacked
4 staple wire plates are aligned.

1 17. (Withdrawn) The system of claim 13 wherein said means for gluing
2 comprises:
3 means for applying glue to substantially all of a surface area of at least
4 one of said sets of adjacent surfaces.

1 18. (Withdrawn) The system of claim 13 wherein said means for gluing
2 comprises:
3 means for applying glue to substantially less than all of a surface area of at
4 least one of said sets of adjacent surfaces.